

Abstract of the Disclosure

A wafer cleaning apparatus with multiple wash-heads is applied in chemical and mechanical polishing process after wafer cleaning. The wafer cleaning apparatus device includes a supporting base, which supporting base
5 comprises a driving device and at least one fluid pipe. A rotation module is also included in the wafer cleaning apparatus. The top side of the rotation module is connected with the driving device. Besides, the rotation module comprises multiple wash-heads and at least one nozzle. The bottom side of wash-head here is contacted with the surface of the wafer. By using driving device, the
10 rotation module can be wholly driven. Also, multiple wash-heads can rotate individually along a cleaning path for cleaning wafer. The fluid was jetted from nozzle and assistant to clean wafer through fluid pipe. The prior art of single wafer wash-head is easily to reform a cleaning dead angle in wafer cleaning process.